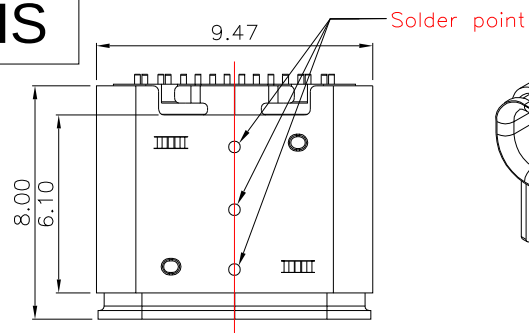
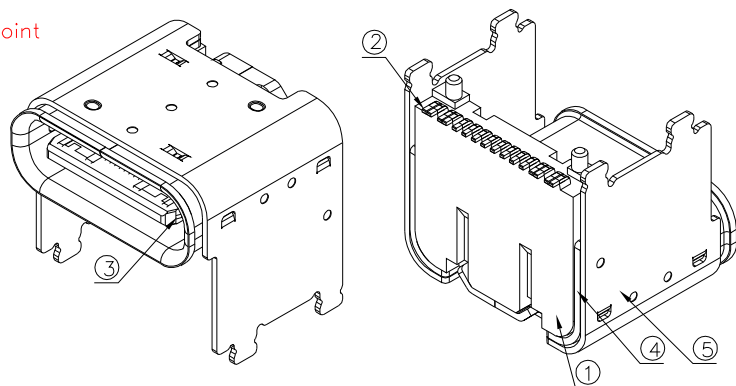


ROHS



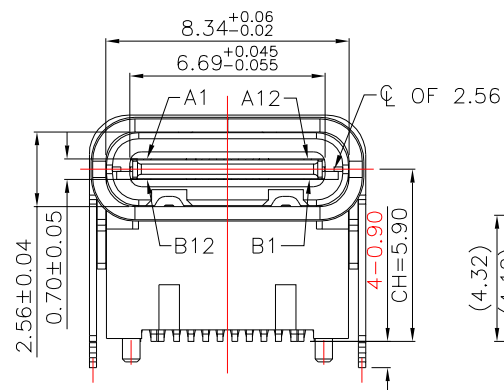
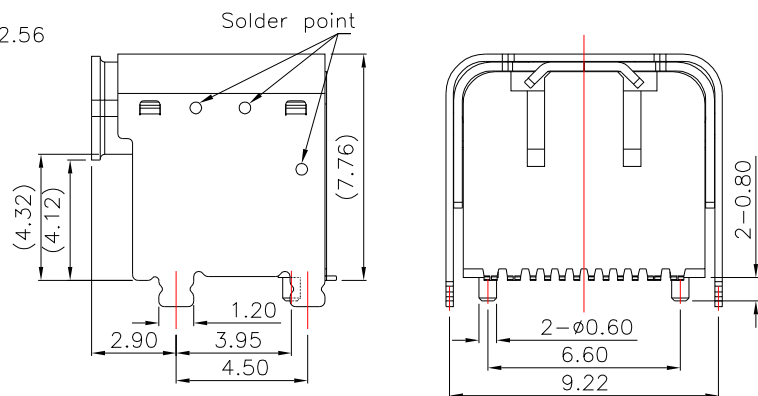
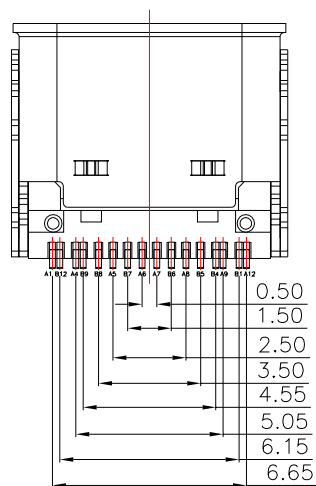
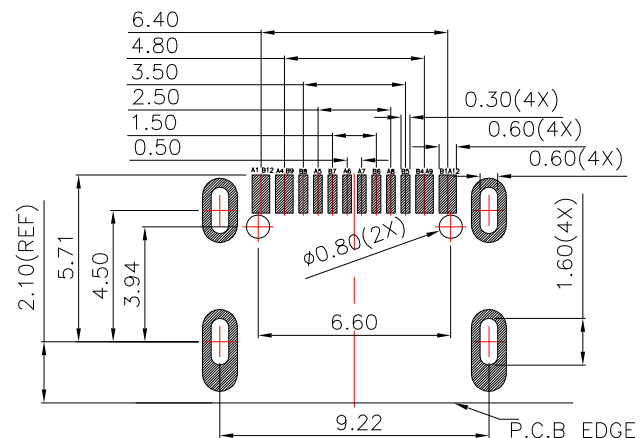
NOTE:

1. MATERIAL SPECIFICATION:
 1. HOUSING: PA10T, UL94 V-0.
 2. CONTACTS: C2680, T=0.15mm
 3. MID PLATE: SUS301, T=0.15mm
 4. INSIDE SHELL: SUS304, T=0.30mm
 5. OUTSIDE SHELL: SUS304, T=0.25mm
2. PLATING SPECIFICATION:
 - 2-1. CONTACTS:

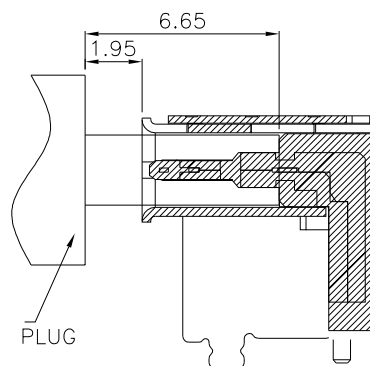
Ni 50u" MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW THE P/N)
GOLD FLASH PLATING ON SOLDER AREA
 - 2-2. INSIDE SHELL OR OUTSIDE SHELL:

Ni 30u" MIN. UNDER PLATED OVER ALL.
 3. MECHANICAL PERFORMANCE,
 - 3-1. INSERTION FORCE: 5~20N.
 - 3-2. REMOVAL FORCE: 8~20N.
 - 3-3. DURABILITY: 10000 CYCLES.
 4. ELECTRICAL PERFORMANCE,
 - 4-1. CURRENT RATING: 5A
VOLTAGE RATING: 20V
 - 4-2. INSULATION RESISTANCE: 100MΩ MIN
 - 4-3. DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.
 - 4-4. LOW CONTACT RESISTANCE: INITIAL 40MΩ / AFTER 50MΩ
 5. ENVIRONMENTAL PERFORMANCE:

OPERATING TEMPERATURE: -30°C~+85°C.



RECOMMEND P.C.B LAYOUT(COMPONENT SIDE)
TOLERANCE FOR PCB LAYOUT IS ± 0.05



A1	GND	B12	GND
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	DP1	B7	DN2
A7	DN1	B6	DP2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A12	GND	B1	GND
PIN	SIGNAL	PIN	SIGNAL

APPROVALS		DATE				
DRAWN						
CHECKED				TITLE:		
APPROVALS				PART NO.		
TOLERANCES ARE	30~...	±0.30	ANGLE	UNIT: mm	SCALE: 1:1	PROJ: 
	10~30	±0.25				
	5~10	±0.20				
	~ 5	±0.15				
			±2°	DRAWING NO.	_____	SHEET 1 OF 1

_____	A	_____	NEW	_____	_____	_____
ECN NO.	REV.	DATE.	DESCRIPTION.	CHANGE.	CHECK.	APPRO.